



Initial Product/Process Change Notification

Document #: IPCN26979ZC1

Issue Date: 03 Aug 2026

Title of Change:	Update to IPCN26979ZC - Wafer Fab and Test Site Change for Ignition IGBT Products from Mountain Top, USA to Bucheon, Korea.
Proposed Changed Material First Ship Date:	20 Feb 2027 or earlier if approved by customer
Current Material Last Order Date:	31 May 2026 <i>Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.</i>
Current Material Last Delivery Date:	31 Dec 2027 <i>The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory.</i>
Product Category:	Active components – Discrete components
Contact information:	Contact your local onsemi Sales Office
PCN Samples Contact:	Contact your local onsemi Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Contact your local onsemi Sales Office
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 6 months prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>
Change Category	
Category	Type of Change
Process - Wafer Production	SEM-PW-01: New / change of wafer substrate material, SEM-PW-02: New wafer diameter, SEM-PW-13: Move all or parts of production to a different wafer fab site.
Test Flow	SEM-TF-01: Move of all or part of electrical wafer test and/or final test to a different test site.
Equipment	SEM-EQ-02: Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool) without change of process.
Description and Purpose:	
This Update Notification is to inform customers of the qualification of onsemi Bucheon, Korea facility as NEW wafer fab site for Ignition IGBT Technology. FPCNs to be issued in November of 2026 with first ship date as referenced above from Bucheon fab. If your FPCN approval will extend beyond the proposed first ship date, provide unit requirements for the unchanged material to your onsemi sales representative no later than May 31, 2026 by NCNR PO (Last order date for unchanged material). These bridge quantities will be limited and will be considered on a first come, first serve basis. onsemi will work with customers to facilitate the approval of the FPCNs by providing early samples and matching electrical data prior to the final PCN notices in November of 2026 to reduce customers need for additional unchanged material. Early samples are processed according to final process and condition as release in the FPCN. No changes will occur between early samples and after FPCN issuance.	



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	Before Change Description	After Change Description
FAB Site	Mountain Top, PA, USA	Bucheon 6 inch
Backgrind Site	Mountain Top, PA, USA	Bucheon 6 inch
Probe Site	Mountain Top, PA, USA and onsemi Bucheon, Korea	onsemi Bucheon, Korea
Wafer size	8 inch	6 inch
OPN naming	No change	-BK suffix added

Reason / Motivation for Change: Source/Supply/Capacity Changes Process/Materials Change

Anticipated impact on fit, form, function, reliability, product safety or manufacturability: The device will be qualified and validated based on the same Product Specification. No anticipated impacts.

Sites Affected:

onsemi Sites	External Foundry/Subcon Sites
onsemi Bucheon, Korea	None

Marking of Parts/ Traceability of Change: The changed material can be identified by lot code and date code.

Qualification Plan:

QV DEVICE NAME : ISL9V5045S3ST-F085
RMS : 98295
PACAKAGE : D2PAK

Test	Specification	Condition	Interval
High Temperature Reverse Bias	JESD22-A108	Tj = Max rate Tj for device, bias =100% of rated V (Not to exceed max rated)	1,008 hrs
High Temperature Gate Bias	JESD22-A108	Tj = Max rate Tj for device, Max Vgs	1,008 hrs
High Temperature Storage Life	JESD22-A103	Ta =Max rate storage temp for device	1,008 hrs
Precondition (PC)	J-STD-020, JESD22-A113	IR reflow at 245C	-
(PC+) Highly Accelerated Stress Test	JESD22-A110	Temp = 130C, 85% RH, ~ 18.8 psig, bias = 80% of rated V or 100V max	96 hrs
(PC+) Unbiased Highly Accelerated Stress Test	JESD22-A118	Temp = 130C, RH=85%, ~ 18.8 psig	96 hrs
(PC+) Temp Cycling	JESD22-A104	Temp = -55°C to +150°C	1,000 cyc
(PC+) Intermittent Operating Life	MIL STD750, M 1037, AEC Q101	Ta=+25°C, deltaTj=100°C max, 3.5 min Ton=Toff	8,527 cyc

QV DEVICE NAME : LV9975UVC-XH
RMS : 98298
PACAKAGE : SIP-6

Test	Specification	Condition	Interval
High Temperature Reverse Bias	JESD22-A108	Tj = Max rate Tj for device, bias =100% of rated V (Not to exceed max rated)	1,008 hrs
Highly Accelerated Stress Test	JESD22-A110	Temp = 130C, 85% RH, ~ 18.8 psig, bias = 80% of rated V or 100V max	96 hrs

QV DEVICE NAME : FGD3245G2-F085
RMS : 98297
PACAKAGE : DPAK

Test	Specification	Condition	Interval
High Temperature Storage Life	JESD22-A103	Ta =Max rate storage temp for device	1,008 hrs
Precondition (PC)	J-STD-020, JESD22-A113	IR reflow at 260C	-
(PC+) Highly Accelerated Stress Test	JESD22-A110	Temp = 130C, 85% RH, ~ 18.8 psig, bias = 80% of rated V or 100V max	96 hrs
(PC+) Unbiased Highly Accelerated Stress Test	JESD22-A118	Temp = 130C, RH=85%, ~ 18.8 psig	96 hrs
(PC+) Temp Cycling	JESD22-A104	Temp = -55°C to +150°C	1,000 cyc
(PC+) Intermittent Operating Life	MIL STD750, M 1037, AEC Q101	Ta=+25°C, deltaTj=100°C max, 2 min Ton=Toff	15,000 cyc

QV DEVICE NAME : FGB5065G2-F085
RMS : 105743
PACAKAGE : D2PAK

Test	Specification	Condition	Interval
High Temperature Reverse Bias	JESD22-A108	Tj = Max rate Tj for device, bias =100% of rated V (Not to exceed max rated)	1,008 hrs
Precondition (PC)	J-STD-020, JESD22-A113	IR reflow at 245C	-
(PC+) Highly Accelerated Stress Test	JESD22-A110	Temp = 130C, 85% RH, ~ 18.8 psig, bias = 80% of rated V or 100V max	96 hrs

Electrical Characteristics Summary:

Electrical characteristics of products from Bucheon Korea will match sending fab Moutain Top .

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Current Part Number	New Part Number	Qualification Vehicle
FGP3040G2-F085C	FGP3040G2-F085C-BK	ISL9V5045S3ST-F085
ISL9V3040D3STV	ISL9V3040D3STV-BK	ISL9V5045S3ST-F085
FGD3245G2-F085-1	FGD3245G2-F085-1-BK	ISL9V5045S3ST-F085
FGD3325G2-F085V	FGD3325G2-F085V-BK	ISL9V5045S3ST-F085
FGD3245G2-F085V	FGD3245G2-F085V-BK	ISL9V5045S3ST-F085
FGD3050G2V	FGD3050G2V-BK	ISL9V5045S3ST-F085
FGD3040G2-F085V	FGD3040G2-F085V-BK	ISL9V5045S3ST-F085
FGD3040G2-F085-1	FGD3040G2-F085-1-BK	ISL9V5045S3ST-F085
FGD2040G3-F085	FGD2040G3-F085-BK	ISL9V5045S3ST-F085
FGD1240G2	FGD1240G2-BK	ISL9V5045S3ST-F085
FGI3040G2-F085C	FGI3040G2-F085C-BK	ISL9V5045S3ST-F085
FGB5065G2-F085	FGB5065G2-F085-BK	ISL9V5045S3ST-F085
FGB5056G2-F085	FGB5056G2-F085-BK	ISL9V5045S3ST-F085
FGD3040G2-F085C	FGD3040G2-F085C-BK	ISL9V5045S3ST-F085
ISL9V3040D3ST-F085C	ISL9V3040D3ST-F085C-BK	ISL9V5045S3ST-F085
ISL9V5045S3ST-F085C	ISL9V5045S3ST-F085C-BK	ISL9V5045S3ST-F085
ISL9V3040S3ST-F085C	ISL9V3040S3ST-F085C-BK	ISL9V5045S3ST-F085
FGB3245G2-F085C	FGB3245G2-F085C-BK	ISL9V5045S3ST-F085
FGB3040G2-F085C	FGB3040G2-F085C-BK	ISL9V5045S3ST-F085